



Product Change Notification

113938 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 113938 - 00
Change Title: Intel® True Scale Fabric Host Channel Adapter QLE7340CK, Intel® True Scale Fabric Host Channel Adapter QLE7340LCK, Intel® True Scale Fabric Host Channel Adapter QLE7342CK, PCN 113938-00, Product Material, Board Material Change from NPG-170TL to NPG-170N
Date of Publication: July 14, 2015

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date of Samples Availability:	Sep 02, 2015
Date Customer Must be Ready to Receive Post-Conversion Material:	Sep 02, 2015

Description of Change to the Customer:

The board material used in all QLE734x products is being changed from NPG-170TL to NPG-170N due to the EOL status of NPG-170TL. Nan Ya Plastics LLC changed NPG-170TL material to End of Life on 12/2013.

The original NPG-170TL is a dicy-cured material, while the replacement NPG-170N is phenolic-cured. NPG-170N has improved thermal reliability over the old material. However, there was no indication of thermal reliability concerns for QLE734x boards using NPG-170TL. Boards made from either the original or new material demonstrate similar electrical characteristics and overall performance, and they are considered functionally equivalent.

Furthermore, the NPG-170N specifications are also more consistent with the new UL 746E requirement for FR-4.1 halogen free material.

Customer Impact of Change and Recommended Action:

There are no impacts to form, fit, or function. There is no change to the Intel MM Number.

Please contact your local Intel Field Sales Representative if you have any further questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Top Assembly	Pre Change PBA	Post Change PBA
QLE7342CK	924482	IB6413601-03	QIB6410401-03 Rev D	QIB6410401-03 Rev E
QLE7340CK	924483	IB6413601-04	QIB6410401-04 Rev D	QIB6410401-04 Rev E
QLE7340LCK	924486	IB6413601-06	QIB6410401-06 Rev D	QIB6410401-06 Rev E

PCN Revision History:

Date of Revision:

July 14, 2015

Revision Number:

00

Reason:

Originally Published PCN